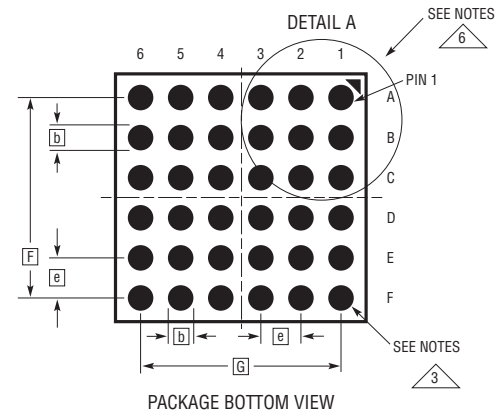
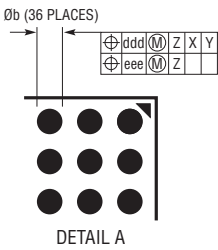
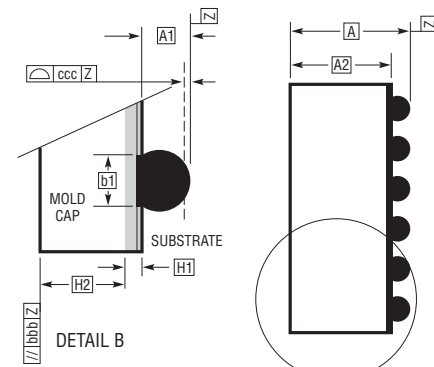
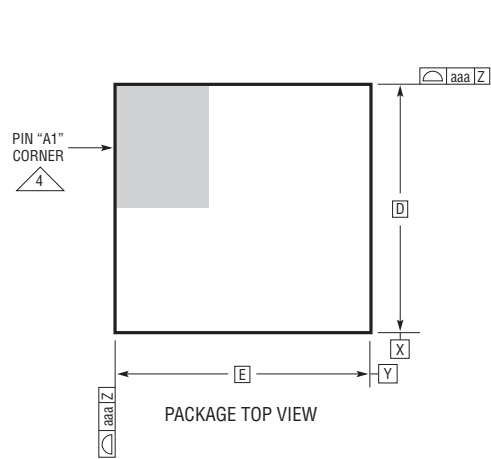
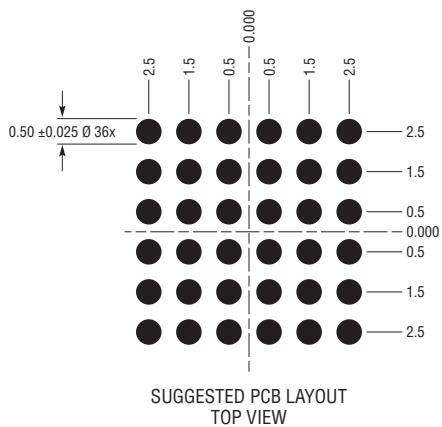


BGA Package
36-Lead (6.25mm × 6.25mm × 2.32mm)
 (Reference LTC DWG # 05-08-1998 Rev A)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.12	2.32	2.52	
A1	0.40	0.50	0.60	BALL HT
A2	1.72	1.82	1.92	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D	6.25			
E	6.25			
e	1.00			
F	5.00			
G	5.00			
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	

TOTAL NUMBER OF BALLS: 36

